imall

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SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company

TIG064E8-

N-Channel IGBT Light-Controlling Flash Applications

Features

- · Low-saturation voltage
- Enhansment type
- Mounting Height 0.9mm, Mounting Area 8.12mm²
- Halogen free compliance

- Low voltage drive (2.5V)
- · Built-in Gate-to-Emitter protection diode
- dv / dt guarantee*

Specifications

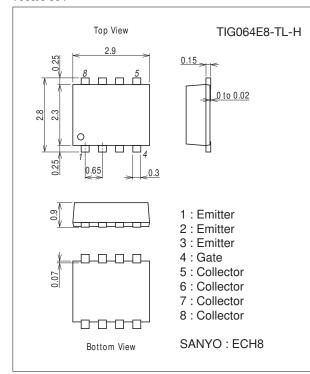
Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Collector-to-Emitter Voltage	VCES		400	V
Gate-to-Emitter Voltage (DC)	VGES		±4	V
Gate-to-Emitter Voltage (Pulse)	VGES	PW≤1ms	±5	V
Collector Current (Pulse)	ICP	V _{GE} =2.5V, C _M =100μF	150	А
Maximum Collector-to-Emitter dv / dt	dV _{CE} / dt	V _{CE} ≤320V, starting Tch=25°C	400	V/μs
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-40 to +150	°C

*: Concerning dv / dt (slope of Collector Voltage at the time of Turn-OFF), dv / dt > 400V / μ s will be 100% screen-detected in the circuit shown as Fig. 1.

Package Dimensions

unit : mm (typ) 7011A-004

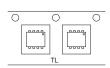


Product & Package Information

- Package : ECH8
- JEITA, JEDEC
- Minimum Packing Quantity : 3000 pcs./reel

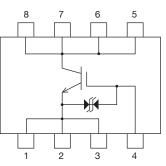
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Packing Type: TL





Electrical Connection

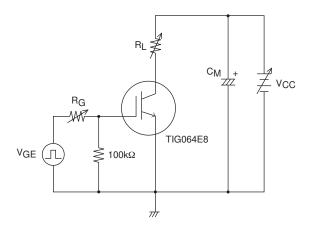


SANYO Semiconductor Co., Ltd. http://semicon.sanyo.com/en/network

Electrical	Characteristics	at Ta=25°C
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Parameter	Symbol	Conditions	Ratings			Unit
Faranieter	Symbol Conditions –		min	typ	max	Unit
Collector-to-Emitter Breakdown Voltage	V(BR)CES	IC=2mA, VGE=0V	400			V
Collector-to-Emitter Cutoff Current	ICES	V _{CE} =320V, V _{GE} =0V			10	μΑ
Gate-to-Emitter Leakage Current	IGES	V _{GE} =±4V, V _{CE} =0V			±10	μΑ
Gate-to-Emitter Threshold Voltage	V _{GE} (off)	V _{CE} =10V, I _C =1mA	0.4		0.9	V
Collector-to-Emitter Saturation Voltage	V _{CE} (sat)	IC=100A, VGE=2.5V		4.2	7	V
Input Capacitance	Cies			3100		pF
Output Capacitance	Coes	V _{CE} =10V, f=1MHz		30		pF
Reverse Transfer Capacitance	Cres			23		pF

Fig.1 Large Current R Load Switching Circuit

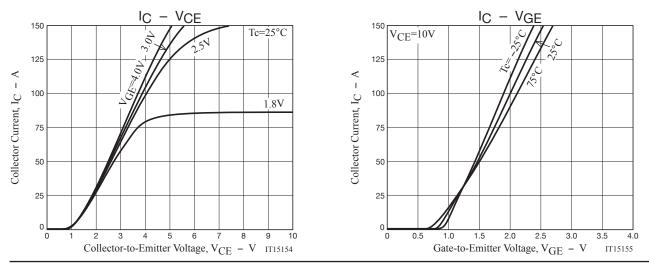


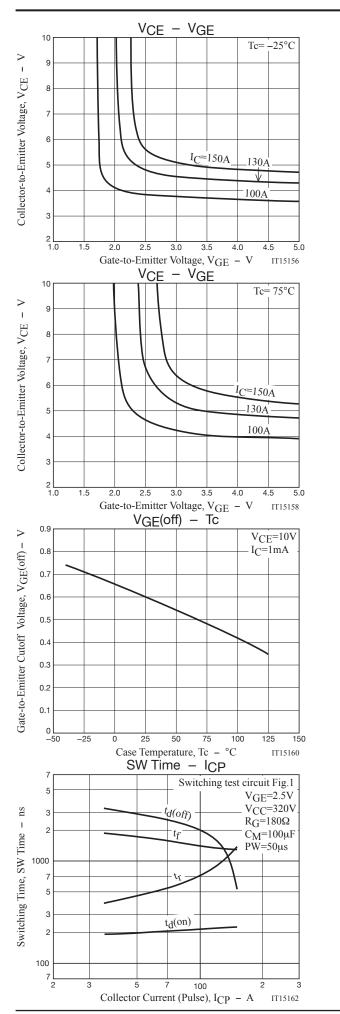
Note1. Gate Series Resistance $R_G \ge 160\Omega$ is recommended for protection purpose at the time of turn OFF. However, if $dv / dt \le 400V / \mu s$ is satisfied at customer's actual set evaluation, $R_G < 160\Omega$ can also be used.

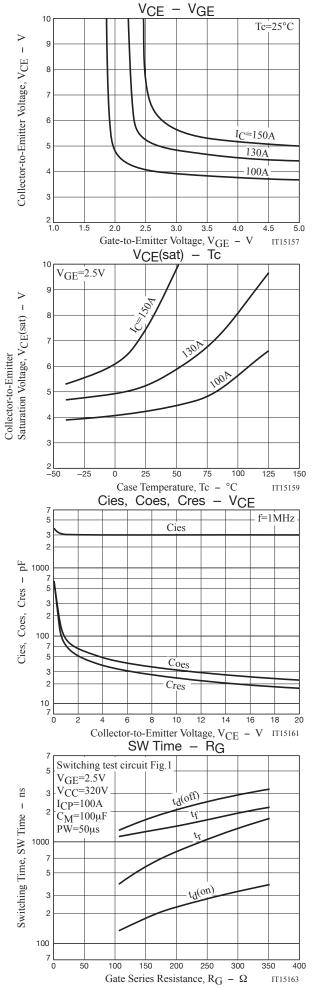
Note2. The collector voltage gradient dv / dt must be smaller than 400V / µs to protect the device when it is turned off.

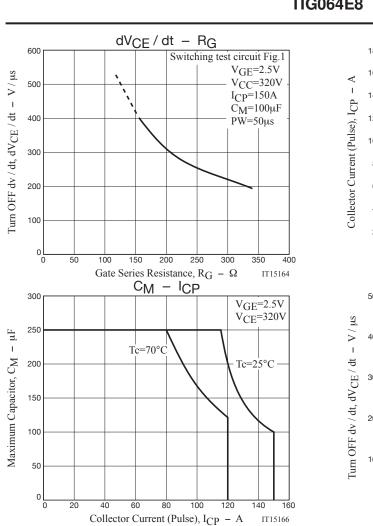
Ordering Information

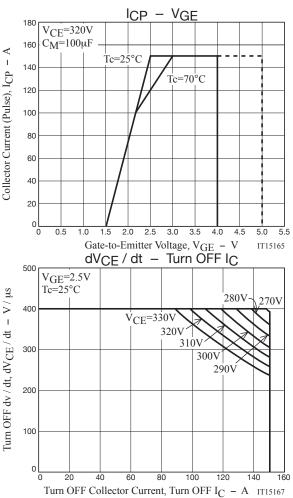
- · · J · · · ·			
Device	Package	Shipping	memo
TIG064E8-TL-H	ECH8	3,000pcs./reel	Pb Free and Halogen Free











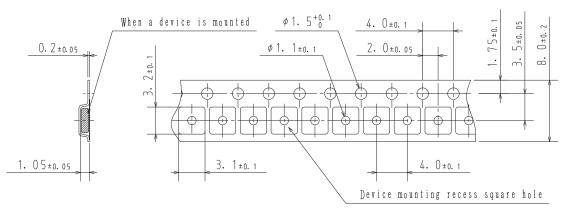
Embossed Taping Specification TIG064E8-TL-H

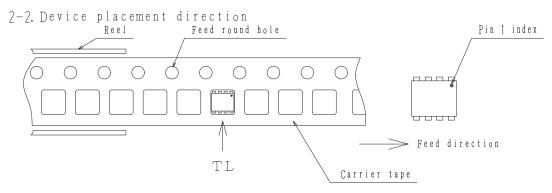
1. Packing Format

ECH8 CPH6 3,000 15,000 90,000 5 reels contained 6 inner boxes contai Dimensions:mm (external) Dimensions:mm (external) Dimensions:mm (external) Dimensions:mm (external) Packing method Reel label, Inner box label Outer box label (un i t:mm) Outer box label Type No. 69 Image: Source of the package 108 (International contents) Type No. Image: Source of the package 108 (International contents) Type No. Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package Image: Source of the package	Package Name	Carrier Tape	Maximum Number of devices contained (pcs)			Packing format		
Dimensions:mm (external) Dimensions:mm (external) Dimensions:mm (external) Dimensions:mm (external) 183×72×185 440×195×21 Reel label, Inner box label (unit:mm) Outer box label It is a label at the time of factory sh The form of a label may change in physi distribution process. Packing method Type No. Image: Comparison of a label may change in physic distribution process. Type No. Comparison of a label may change in physic distribution process. Type Comparison of a label may change in physic distribution process. Comparison of the physic distribution process. Type No. Comparison of a label may change in physic distribution process. Comparison of the physic distribution process. Comparison of a label may change in physic distribution process. Comparison of a label may change in physic distribution process. Comparison of the physic distribution process. Comparison of a label may change in physic distribution process. Comparison of a label may change in physic distribution process. Comparison of the physic distribution process. Comparison of a label may change in physic distribution process. Comparison of a label may change in physic distribution process. Comparison of the physic distribution process. Comparison of a label may change in physic distribution process. Comparison of a label may change in physic distribution process. Comparison of the physic		Туре	Reel	Inner box	Outer box	Inner BOX (C-1) Outer BOX (A-7)		
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Origin Image: Construction of the terminal is lead free, Origin Image: Construction of the terminal is lead free, NOTE (1) The LEAD FREE * description shows that the surface treatment of the terminal is lead free, Label JEITA Phase 3A LEAD FREE 4 JEITA Phase 3A	Packing met	Type LOT Quan Orig	No. tity in	$ \xrightarrow{\text{(P)}} (\overrightarrow{P}) ($	(u: TTYPE 0000C IIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIII	nner box label Outer box label nit:mm) It is a label at the time of factory shipments, The form of a label may change in physical distribution process. 69 108 000000 TYPE CODE 000000 ************************************		

2. Taping configuration

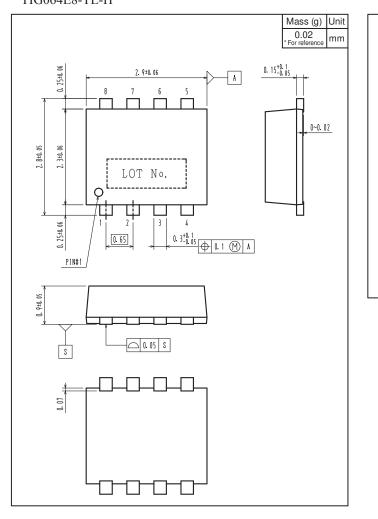
2-1. Carrier tape size (unit:mm)



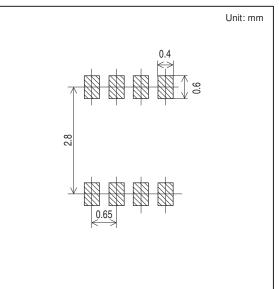


Those with pin 1 index on the feed hole side ·····TL

Outline Drawing TIG064E8-TL-H



Land Pattern Example



Note : TIG064E8 has protection diode between gate and emitter but handling it requires sufficient care to be taken.

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